



## Material Content Data Sheet



<b>Sales Product Name</b>		BGB 741L7ESD E6327		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001613062						
<b>Package</b>		PG-TSLP-7-1		<b>Weight*</b>		1.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1091	
	noble metal	gold	7440-57-5	0.007	0.42		4231	
	inorganic material	silicon	7440-21-3	0.059	3.73	4.26	37252	42574
leadframe	non noble metal	nickel	7440-02-0	0.329	20.85	20.85	208514	208514
wire	noble metal	gold	7440-57-5	0.046	2.90	2.90	29003	29003
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.03		340	
	organic material	carbon black	1333-86-4	0.011	0.68		6798	
	plastics	epoxy resin	-	0.145	9.18		91770	
	inorganic material	silicondioxide	60676-86-0	0.916	58.08	67.97	580873	679781
leadfinish	noble metal	gold	7440-57-5	0.032	2.01	2.01	20064	20064
plating	noble metal	gold	7440-57-5	0.032	2.01	2.01	20064	20064
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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